

### FEATURES

- Double Side Cooling
- High Surge Capability

### APPLICATIONS

- Rectification
- Freewheel Diode
- DC Motor Control
- Power Supplies
- Welding
- Battery Chargers

### VOLTAGE RATINGS

Type Number	Repetitive Peak Reverse Voltage $V_{RRM}$ V	Conditions
DS2103SY26	2600	$V_{RSM} = V_{RRM} + 100V$
DS2103SY25	2500	
DS2103SY24	2400	
DS2103SY23	2300	
DS2103SY22	2200	
DS2103SY21	2100	

Lower voltage grades available.

### ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table, e.g.:

**DS2103SY22** for a 2200V device in a Y outline

or

**DS2103SV22** for a 2200V device in a V outline

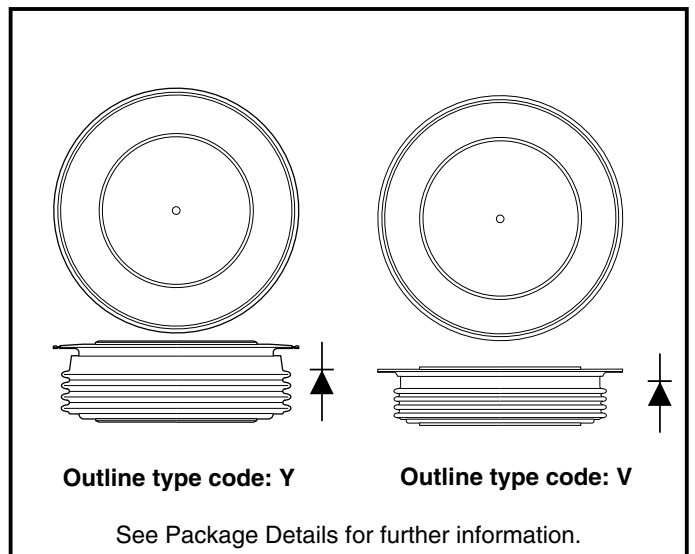
Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

### KEY PARAMETERS

$V_{RRM}$  **2600V**

$I_{F(AV)}$  **5788A**

$I_{FSM}$  **81000A**



**Fig. 1 Package outlines**

## CURRENT RATINGS

$T_{case} = 75^{\circ}\text{C}$  unless otherwise stated

Symbol	Parameter	Conditions	Max.	Units
<b>Double Side Cooled</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	5788	A
$I_{F(RMS)}$	RMS value	-	9076	A
$I_F$	Continuous (direct) forward current	-	8278	A
<b>Single Side Cooled (Anode side)</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	3751	A
$I_{F(RMS)}$	RMS value	-	5892	A
$I_F$	Continuous (direct) forward current	-	4955	A

$T_{case} = 100^{\circ}\text{C}$  unless otherwise stated

Symbol	Parameter	Conditions	Max.	Units
<b>Double Side Cooled</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	4785	A
$I_{F(RMS)}$	RMS value	-	7516	A
$I_F$	Continuous (direct) forward current	-	6725	A
<b>Single Side Cooled (Anode side)</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	3060	A
$I_{F(RMS)}$	RMS value	-	4807	A
$I_F$	Continuous (direct) forward current	-	3950	A

**SURGE RATINGS**

Symbol	Parameter	Conditions	Max.	Units
$I_{FSM}$	Surge (non-repetitive) forward current	10ms half sine; $T_{case} = 175^{\circ}C$	65.0	kA
$I^2t$	$I^2t$ for fusing	$V_R = 50\% V_{RRM}$ - 1/4 sine	$21.1 \times 10^6$	A <sup>2</sup> s
$I_{FSM}$	Surge (non-repetitive) forward current	10ms half sine; $T_{case} = 175^{\circ}C$	81.0	kA
$I^2t$	$I^2t$ for fusing	$V_R = 0$	$33 \times 10^6$	A <sup>2</sup> s

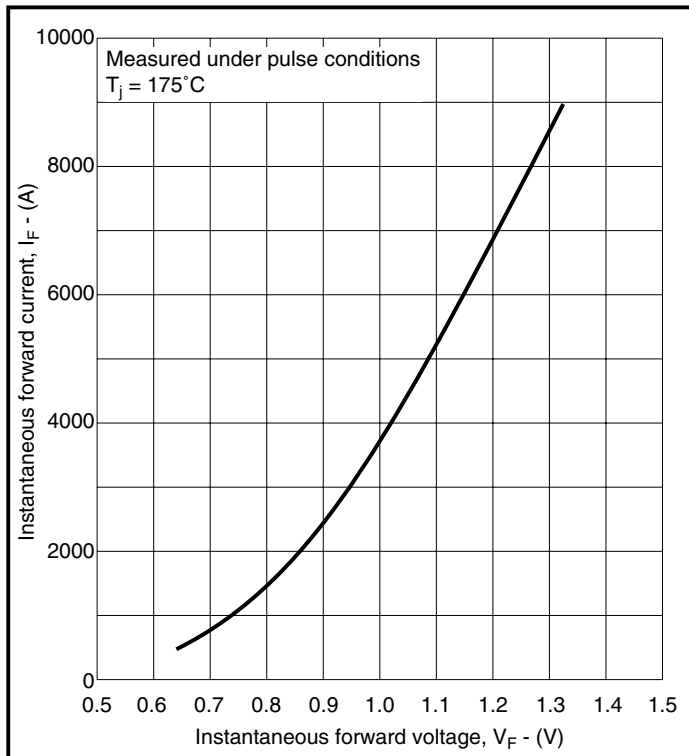
**THERMAL AND MECHANICAL DATA**

Symbol	Parameter	Conditions	Min.	Max.	Units	
$R_{th(j-c)}$	Thermal resistance - junction to case	Double side cooled	dc	-	0.0095	$^{\circ}C/W$
		Single side cooled	Anode dc	-	0.019	$^{\circ}C/W$
			Cathode dc	-	0.019	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Clamping force 43.0kN with mounting compound	Double side	-	0.002	$^{\circ}C/W$
			Single side	-	0.004	$^{\circ}C/W$
$T_{vj}$	Virtual junction temperature	Forward (conducting)	-	200	$^{\circ}C$	
		Reverse (blocking)	-	175	$^{\circ}C$	
$T_{stg}$	Storage temperature range		-55	175	$^{\circ}C$	
-	Clamping force		38.0	47.0	kN	

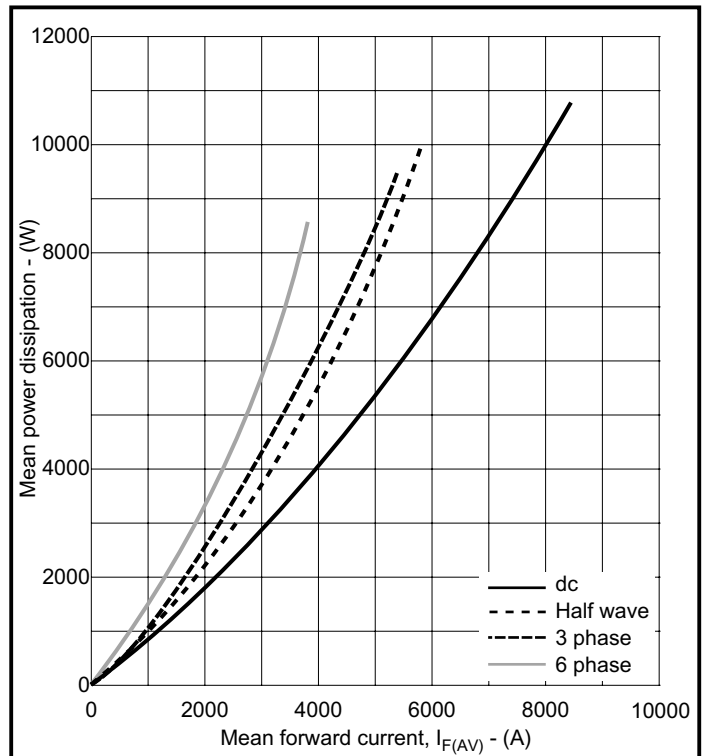
**CHARACTERISTICS**

Symbol	Parameter	Conditions	Min.	Max.	Units
$V_{FM}$	Forward voltage	At 3000A peak, $T_{case} = 25^{\circ}C$	-	1.05	V
$I_{RM}$	Peak reverse current	At $V_{RRM}$ , $T_{case} = 175^{\circ}C$	-	150	mA
$Q_s$	Total stored charge	$I_F = 2000A, di_{RR}/dt = 3A/\mu s$ $T_{case} = 175^{\circ}C, V_R = 100V$	-	3000	$\mu C$
$I_{rr}$	Peak reverse recovery current		-	125	A
$V_{TO}$	Threshold voltage	At $T_{vj} = 175^{\circ}C$	-	0.75	V
$r_T$	Slope resistance	At $T_{vj} = 175^{\circ}C$	-	0.063	m $\Omega$

**CURVES**



**Fig.2 Maximum (limit) forward characteristics**



**Fig.3 Dissipation curves**

$V_{FM}$  Equation:-

$$V_{FM} = A + B \ln(I_F) + C \cdot I_F + D \cdot \sqrt{I_F}$$

Where

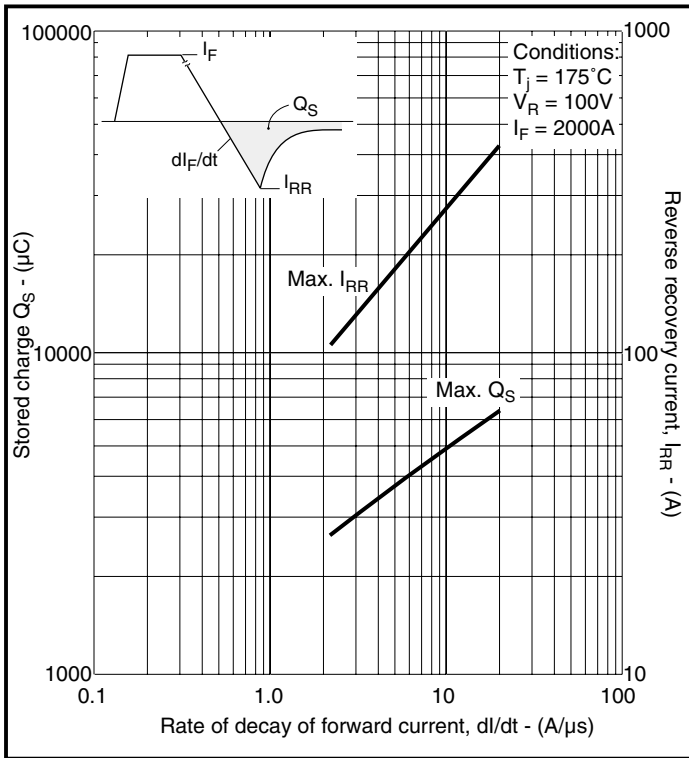
$A = -0.51826$

$B = 0.195881$

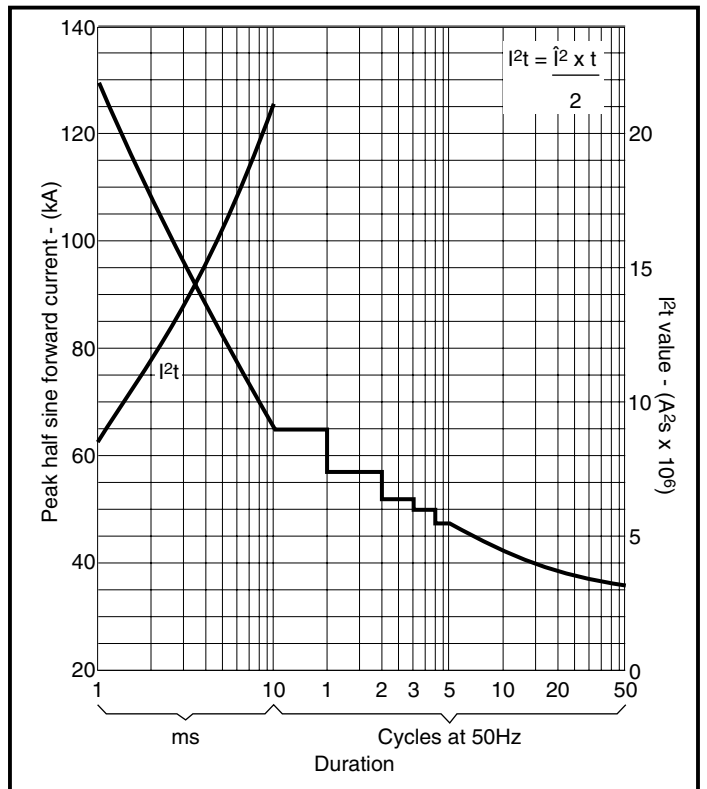
$C = 6.39 \times 10^{-5}$

$D = -0.00544$

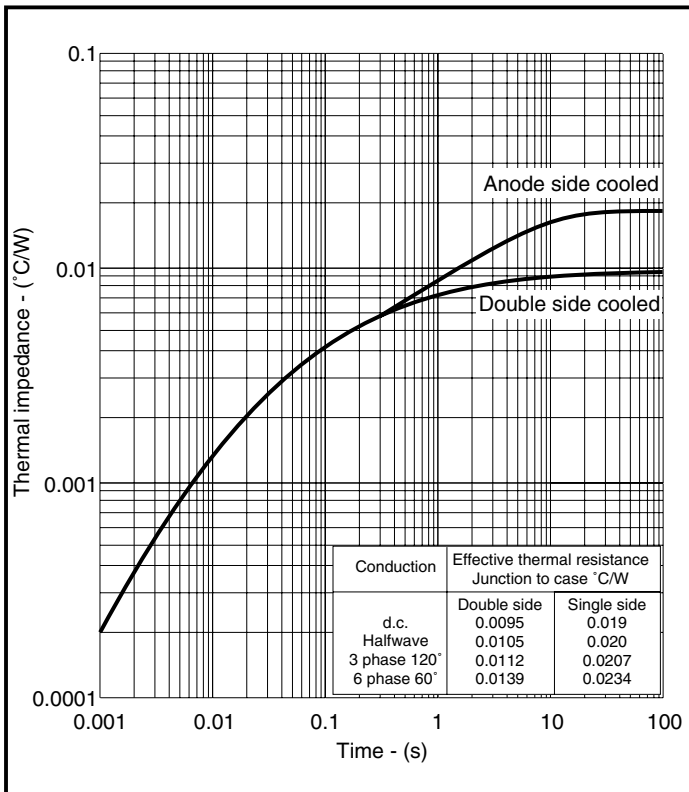
these values are valid for  $T_j = 175^{\circ}C$  for  $I_F$  500A to 9000A



**Fig.4 Total stored charge and maximum reverse recovery current**



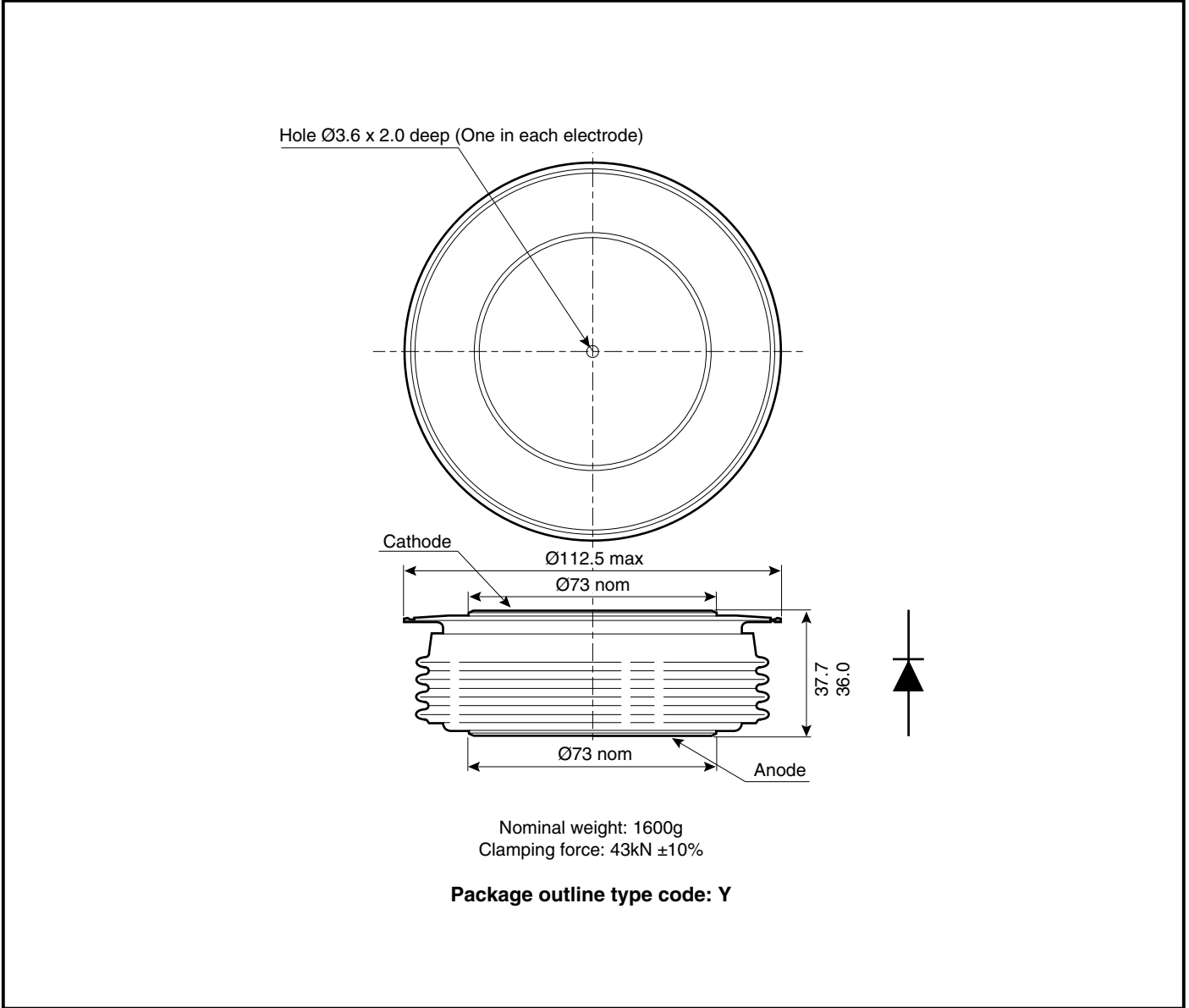
**Fig.5 Surge (non-repetitive) forward current vs time (with 50%  $V_{RRM}$  at  $T_{case} 175^\circ\text{C}$ )**



**Fig.6 Maximum (limit) transient thermal impedance - junction to case**

**PACKAGE DETAILS**

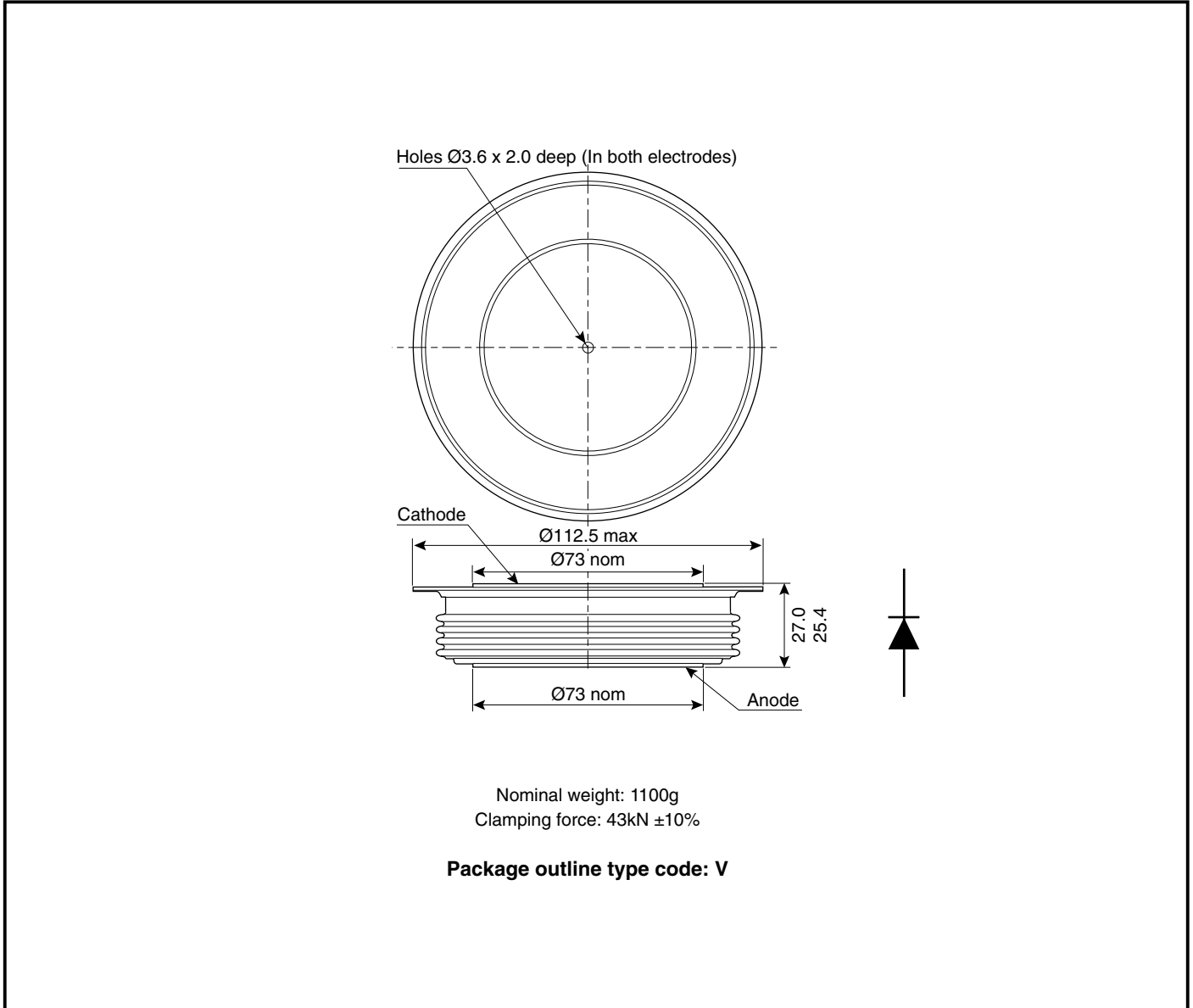
For further package information, please visit our website or contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



**Note:**  
Some packages may be supplied with gate pins and/or tags.

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## POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

## HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.



<http://www.dynexsemi.com>

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